

What is claimed is:

- 1           1.       A method for wire bonding a finger sensor die to an external circuit,  
2       wherein the finger sensor die includes a sensor array having one or more die contacts that  
3       are wire bonded to one or more external contacts of the external circuit so that a usable  
4       portion of the sensor array is maximized, the method comprises steps of:  
5           forming a ball at a first end of a bonding wire;  
6           forming an electrically conductive connection between the ball and a selected  
7       external contact of the external circuit;  
8           extending the bonding wire to a selected die contact so as to form a wire loop  
9       having a low loop height;  
10          forming an electrically conductive stitch connection between a second end of the  
11       bonding wire and the selected die contact; and  
12          repeating the above steps until the one or more die contacts are wire bonded to the  
13       one or more external contacts of the external circuit.